

# LNJ121W84RA

## Ultra High Bright Surface Mounting Chip LED

Dome-Lens Bi-Color Type

**■ Absolute Maximum Ratings**  $T_a = 25^\circ\text{C}$ 

## • Red

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	55	mW
Forward current	$I_F$	20	mA
Pulse forward current	$I_{FP}$	60	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

## • Green

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**■ Lighting Color / Lens Color**

- Red / Clear
- Green / Clear

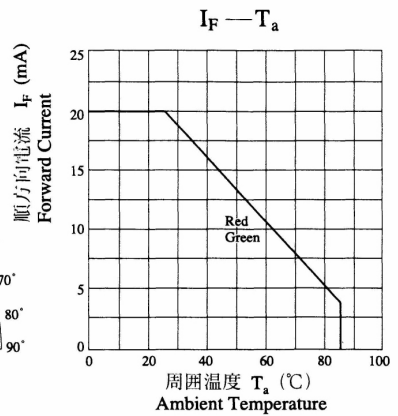
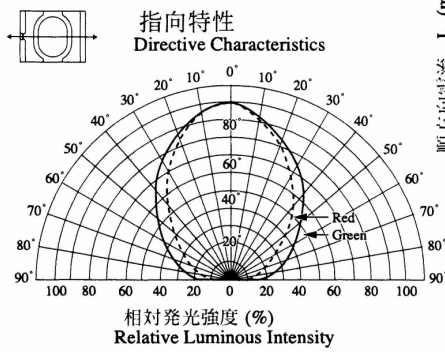
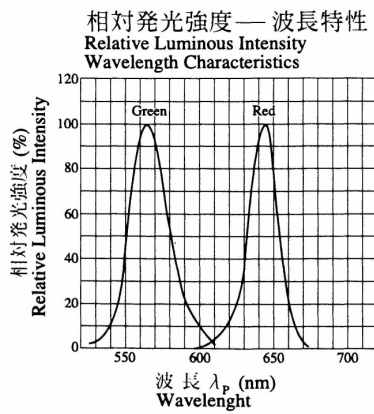
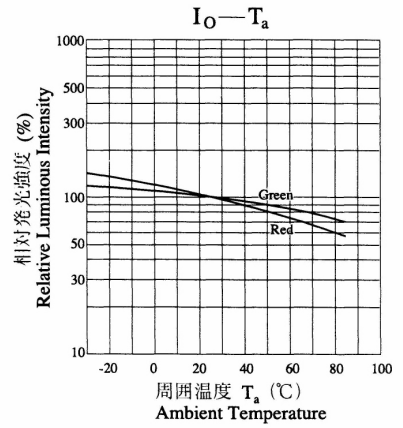
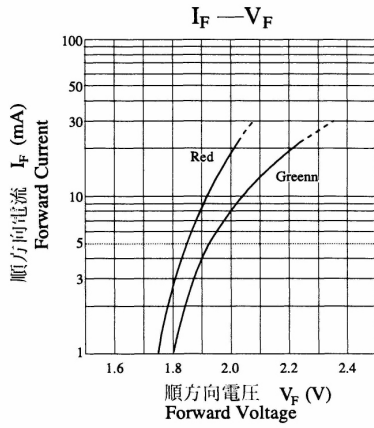
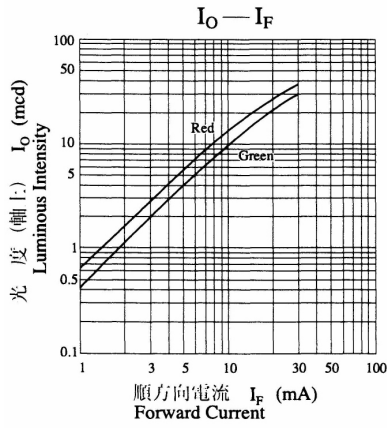
**■ Electro-Optical Characteristics**  $T_a = 25^\circ\text{C}$ 

## • Red

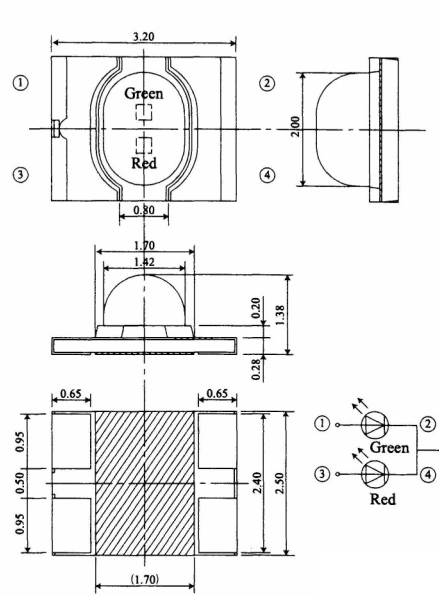
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		7.0	13.4		mcd
Forward current	$I_F$			10		mA
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		1.92	2.5	V
Peak emission wavelength	$\lambda_p$	$I_F = 10\text{ mA}$		645		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		22		nm
Reverse current	$I_R$	$V_R = 4\text{ V}$			100	$\mu\text{A}$

## • Green

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		5.0	10		mcd
Forward current	$I_F$			10		mA
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		2.03	2.6	V
Peak emission wavelength	$\lambda_p$	$I_F = 10\text{ mA}$		565		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		30		nm
Reverse current	$I_R$	$V_R = 4\text{ V}$			10	$\mu\text{A}$



■ Package (Unit: mm)



• Pin name

1, 3: Anode

2, 4: Cathode

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